

[ABSTRACT]

The present invention involves performing (a) a step for supplying a first feedstock gas to a substrate where a recessed structure has been provided to a surface thereof, and forming a first film having a prescribed adhesive force on an inner surface of the recessed structure, and (b) a step for supplying a second feedstock gas to the substrate, and forming, on the first film, a second film having a lower adhesive force than the adhesive force of the first film.